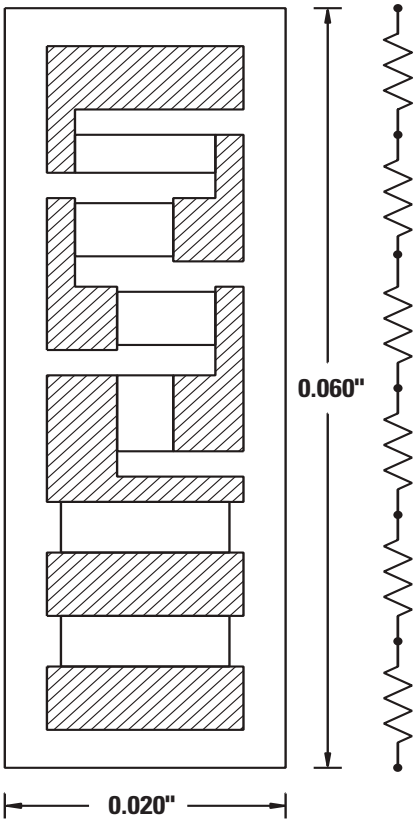
THIN FILM MULTI-TAP RESISTORS

MSMT 116 SERIES LOG RESISTOR



MECHANICAL DATA

SIZE	0.060" x 0.020" x 0.010" (±0.003")
SUBSTRATE	SILICON OR ALUMINA
RESISTOR	TANTALUM NITRIDE
BOND PADS	25,000 Å MINIMUM GOLD
BACKSIDE SURFACE	BARE SUBSTRATE GOLD BACK OPTIONAL. SUITABLE FOR EUTECTIC DIE ATTACH

ELECTRICAL DATA

RESISTANCE RANGE	240Ω TOTAL (SIX RESISTIVE ELEMENTS, 10Ω, 10Ω, 20Ω, 50Ω, 50Ω, AND 100Ω)
TOLERANCE	5% OR 10% (APPLIES TO INDIVIDUAL RESISTIVE ELEMENTS)
T.C.R.	±150ppm/°C STANDARD
NOISE	-20dB MAX
POWER RATING TO 70°C	125mW
OPERATING VOLTAGE	100V MAX
SHORT TERM OVERLOAD	5X RATED POWER, 25°C, 5 SEC., ±0.25% MAX. ΔR/R: ±0.1% MSI TYPICAL
HIGH TEMP. EXPOSURE	150°C, 100 HRS., ±0.25% MAX. ΔR/R: ±0.03% MSI TYPICAL
THERMAL SHOCK	MIL-STD 202, METHOD 107F, ±0.25% MAX. ΔR/R: ±0.1% MSI TYPICAL
MOISTURE RESISTANCE	MIL-STD 202, METHOD 106, ±0.5% MAX. ΔR/R: ±0.1% MSI TYPICAL
STABILITY	1000 HRS., 70°C, 100% POWER, ±0.5% MAX. ΔR/R: ±0.1% MSI TYPICAL
OPERATING TEMP. RANGE	-55°C TO +125°C

PART NUMBER DESIGNATION

MSMT	X	—	T	—	XXXXX	X	—	X
SERIES	SUBSTRATE		RESISTIVE FILM		OHMIC VALUE	TOLERANCE		OPTION DESIGNATOR
116	A = Alumina S = Silicon		T = Tantalum Nitride		5-Digit Number: 1st 4 Digits Are Significant With "R" As Decimal Point When Required. 5th Digit Represents Number of Zeros.	J = 5% K = 10%		GB = Gold Backside G = Gold Bond Pads

EXAMPLES: MSMT 116AT-240R0J-GB = 240Ω, ±5%
Alumina Substrate, Gold Backside.

Consult Sales for other values / configurations

NETWORKS & ARRAYS

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